

Title (en)

FABRICATION OF CONDUCTIVE NANOSTRUCTURES ON A FLEXIBLE SUBSTRATE

Title (de)

HERSTELLUNG VON LEITENDEN NANOSTRUKTUREN AUF EINEM FLEXIBLEN SUBSTRAT

Title (fr)

FABRICATION DE NANOSTRUCTURES CONDUCTRICES SUR UN SUBSTRAT FLEXIBLE

Publication

EP 2370348 A4 20161221 (EN)

Application

EP 09836644 A 20091202

Priority

- US 2009066302 W 20091202
- US 13827208 P 20081217

Abstract (en)

[origin: WO2010077529A2] Provided is a method of fabricating a continuous nanostructured material having an electrodeposited surface layer. A conductive master drum having a relief pattern on its surface that exposes only a portion of the master drum surface is immersed into a plating bath. An electrodepositable material is coated onto the exposed surface of the drum. A support material is coated over the deposited layer and the relief structure. Removal from the drum yields the nanostructured material.

IPC 8 full level

B82B 3/00 (2006.01); **B82B 1/00** (2006.01); **B82Y 20/00** (2011.01); **C25D 1/00** (2006.01); **C25D 5/02** (2006.01); **G02B 5/30** (2006.01)

CPC (source: EP KR US)

B82B 1/00 (2013.01 - KR); **B82B 3/00** (2013.01 - KR); **B82Y 20/00** (2013.01 - EP US); **C25D 1/003** (2013.01 - EP US); **C25D 1/006** (2013.01 - EP US); **C25D 5/02** (2013.01 - EP US); **C25D 5/028** (2013.01 - EP US); **B82Y 40/00** (2013.01 - KR); **G02B 5/3025** (2013.01 - EP US); **G02B 2207/101** (2013.01 - EP US)

Citation (search report)

- [X1] WO 2008081904 A1 20080710 - HITACHI CHEMICAL CO LTD [JP], et al & US 2010021695 A1 20100128 - NAOYUKI SUSUMU [JP], et al
- [X1] EP 1527216 A2 20050504 - INFINEON TECHNOLOGIES AG [DE]
- See references of WO 2010077529A2

Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

US 2009066302 W 20091202; CN 200980155613 A 20091202; EP 09836644 A 20091202; KR 20117016221 A 20091202; US 200913130064 A 20091202